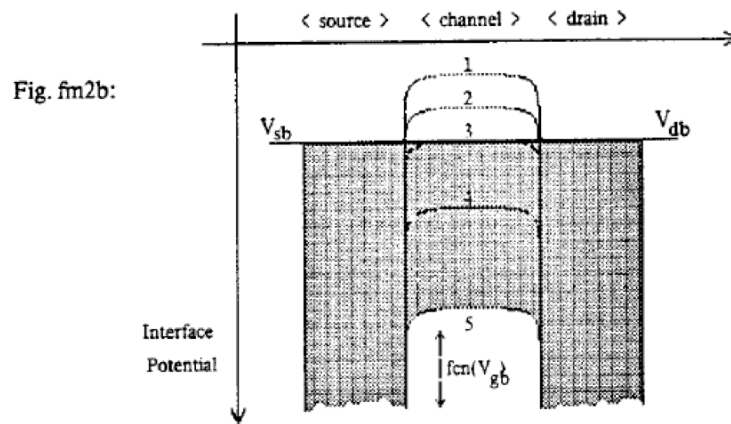
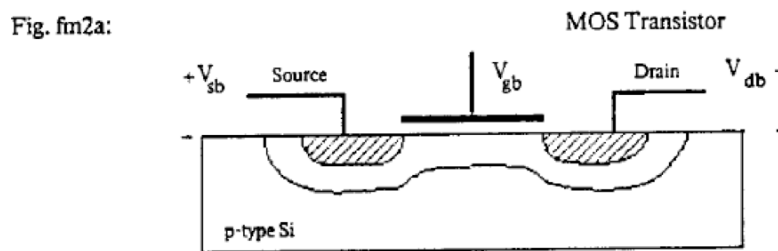
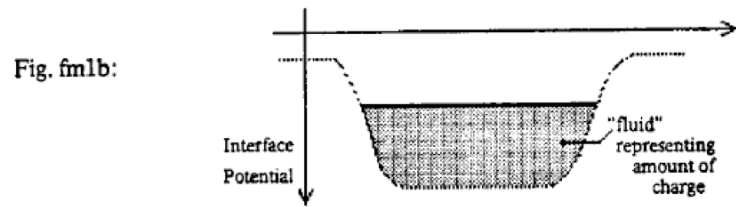
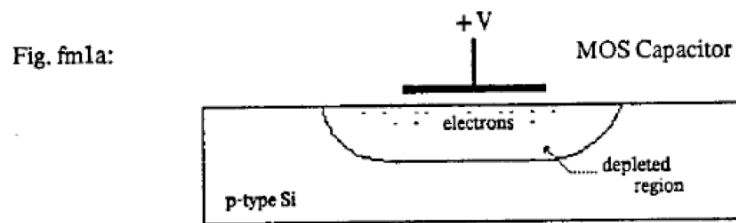


520.216

Lecture 5
MOS Transistor Model

Andreas G. Andreou

MOS transistor revisited (I)



From: Introduction to VLSI Mead and Conway

MOS structure

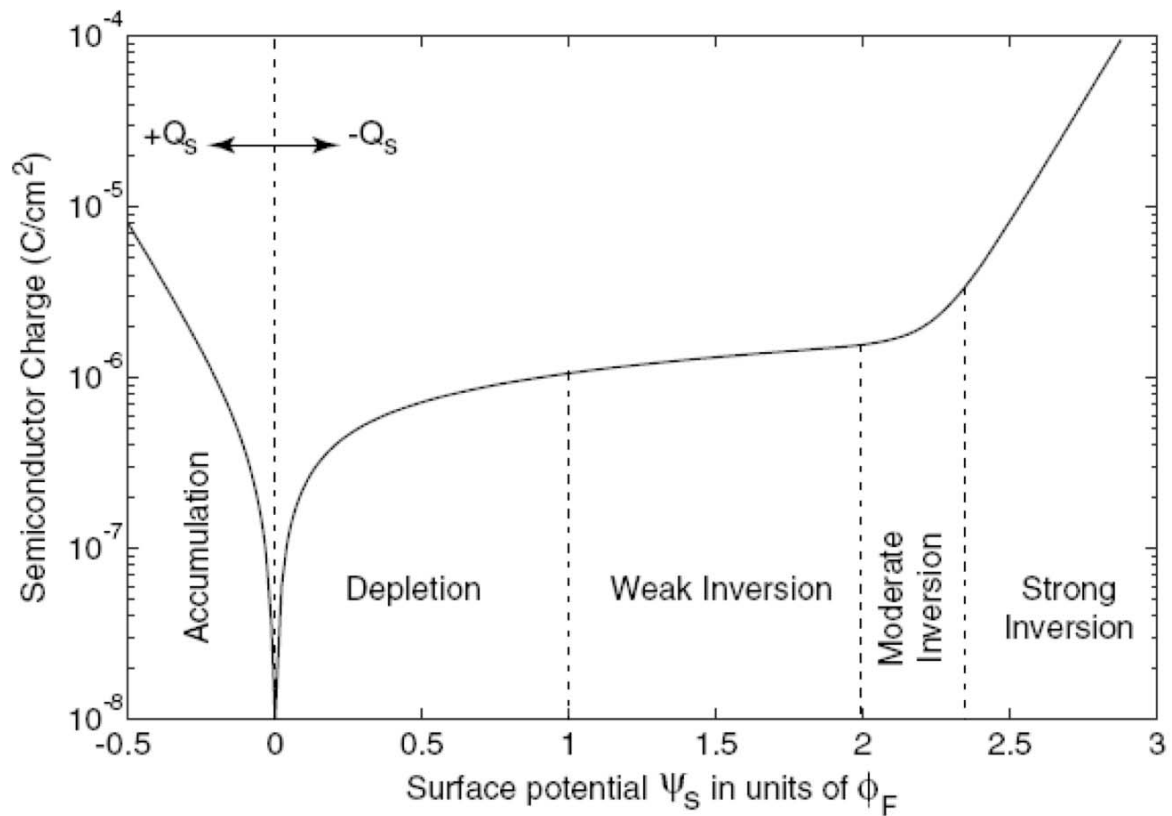
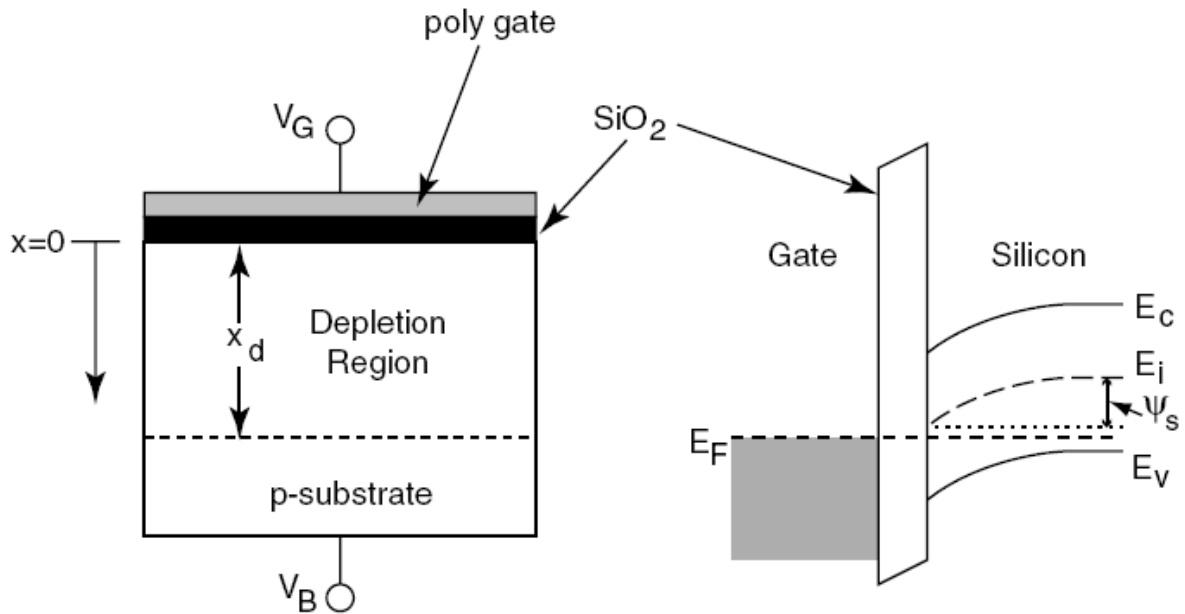
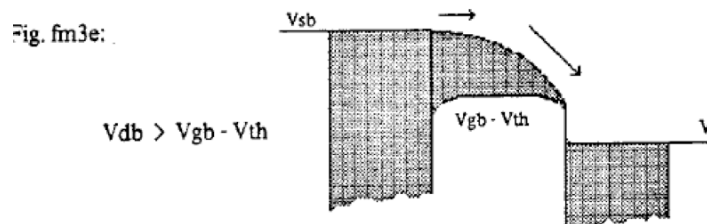
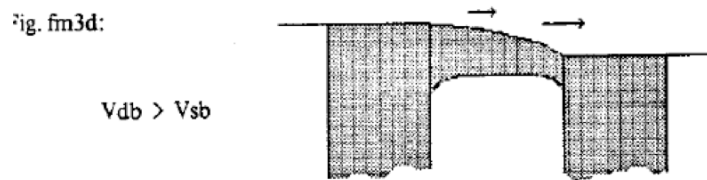
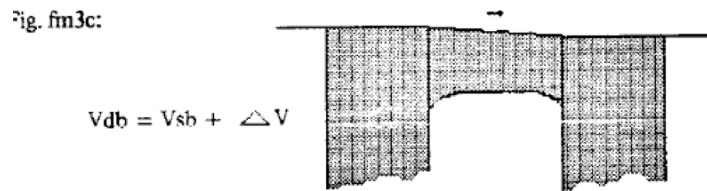
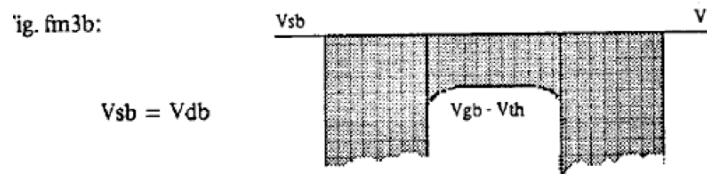
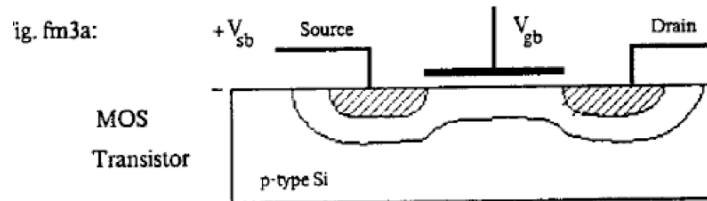


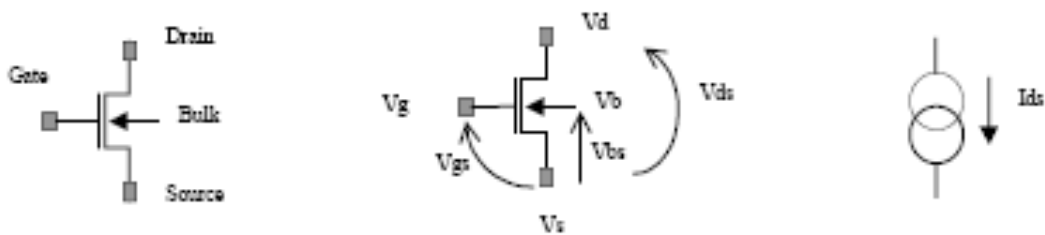
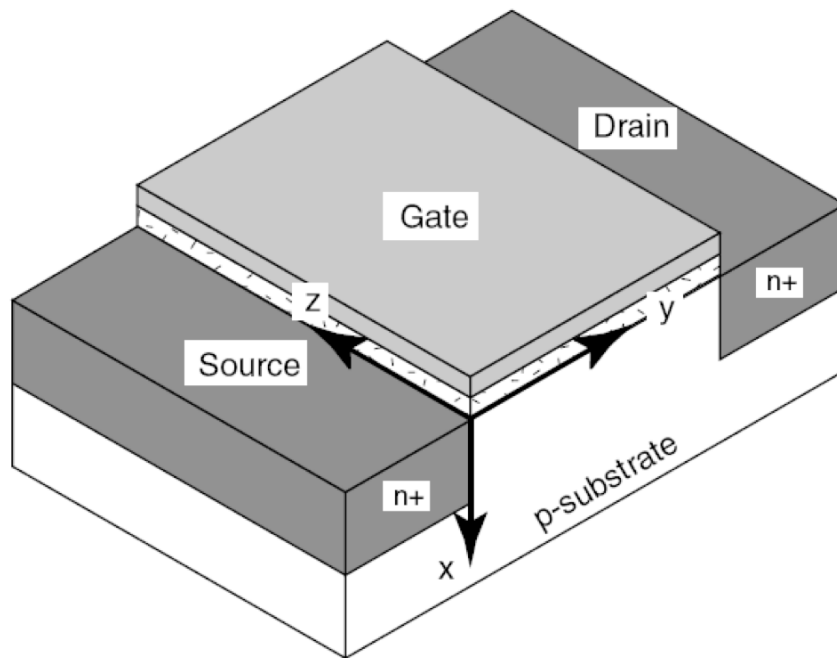
Figure 2.2: Semiconductor charge per cm² vs. surface potential for a MOS structure doped at $N_A = 7 \times 10^{15}/\text{cm}^3$.

MOS transistor revisited (II)



From: Introduction to VLSI Mead and Conway

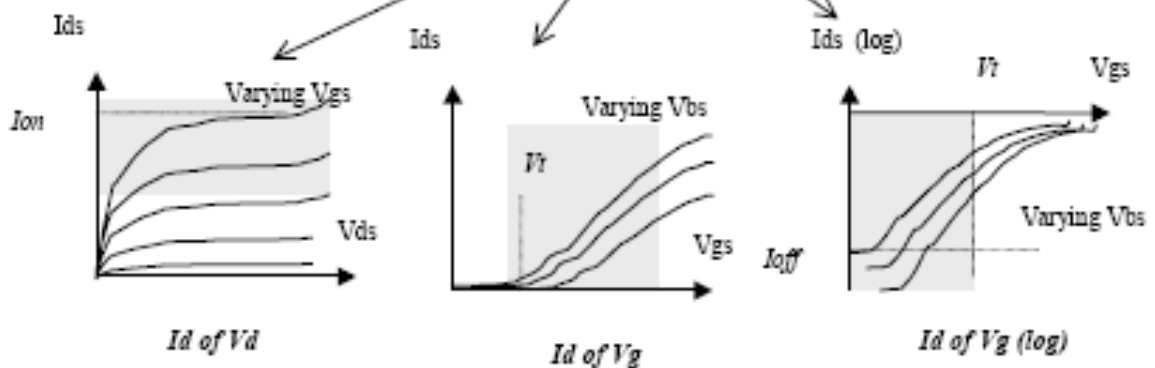
MOS Transistor



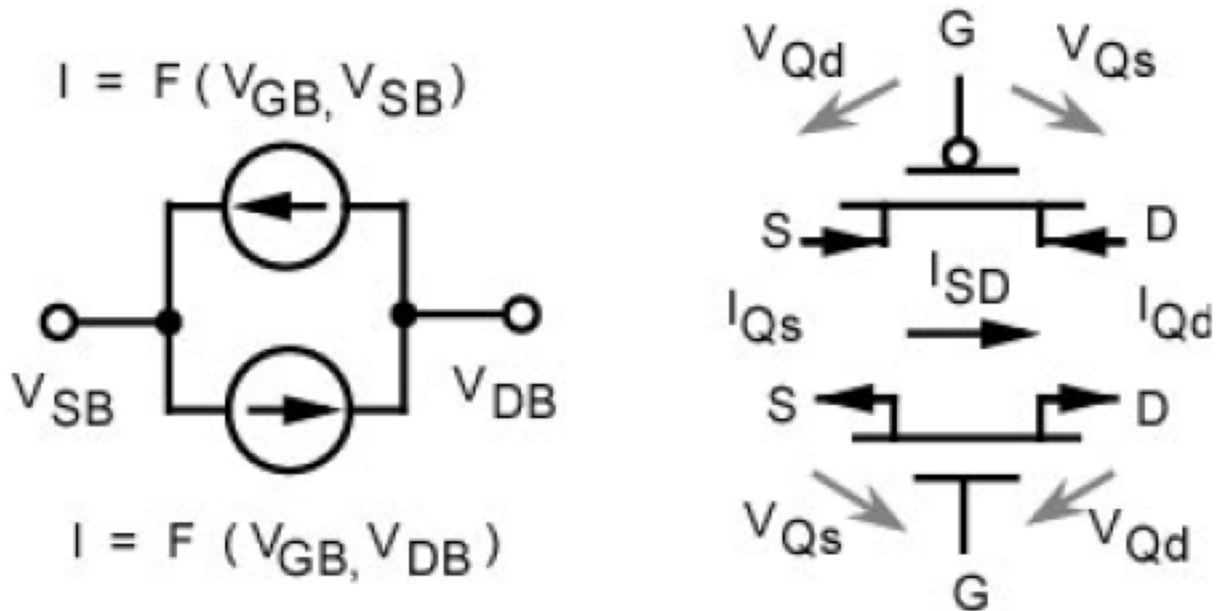
$$I_{ds} = f(V_d, V_g, V_s, V_b)$$

(eq 3-1)

$$I_{ds} = f(v_d, v_s, v_g, v_b)$$



SYMMETRIC MOS MODEL



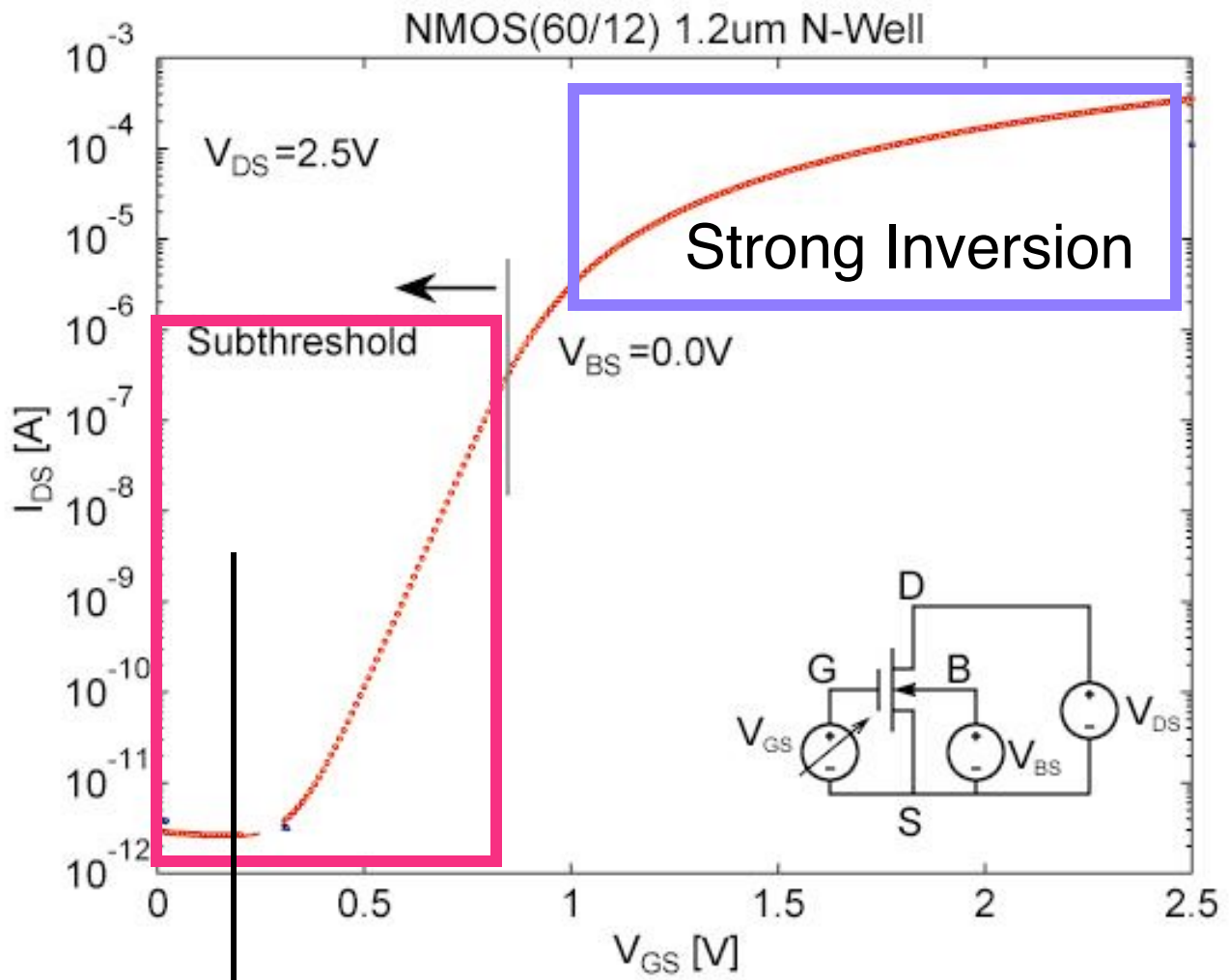
$$I_{SD} \propto F(V_{GB}, V_{SB}) - F(V_{GB}, V_{DB})$$

WEAK INVERSION REGION

$$I_{SD} \propto G(V_{GB}) [H(V_{SB}) - H(V_{DB})]$$

Weak (vs) Strong Inversion

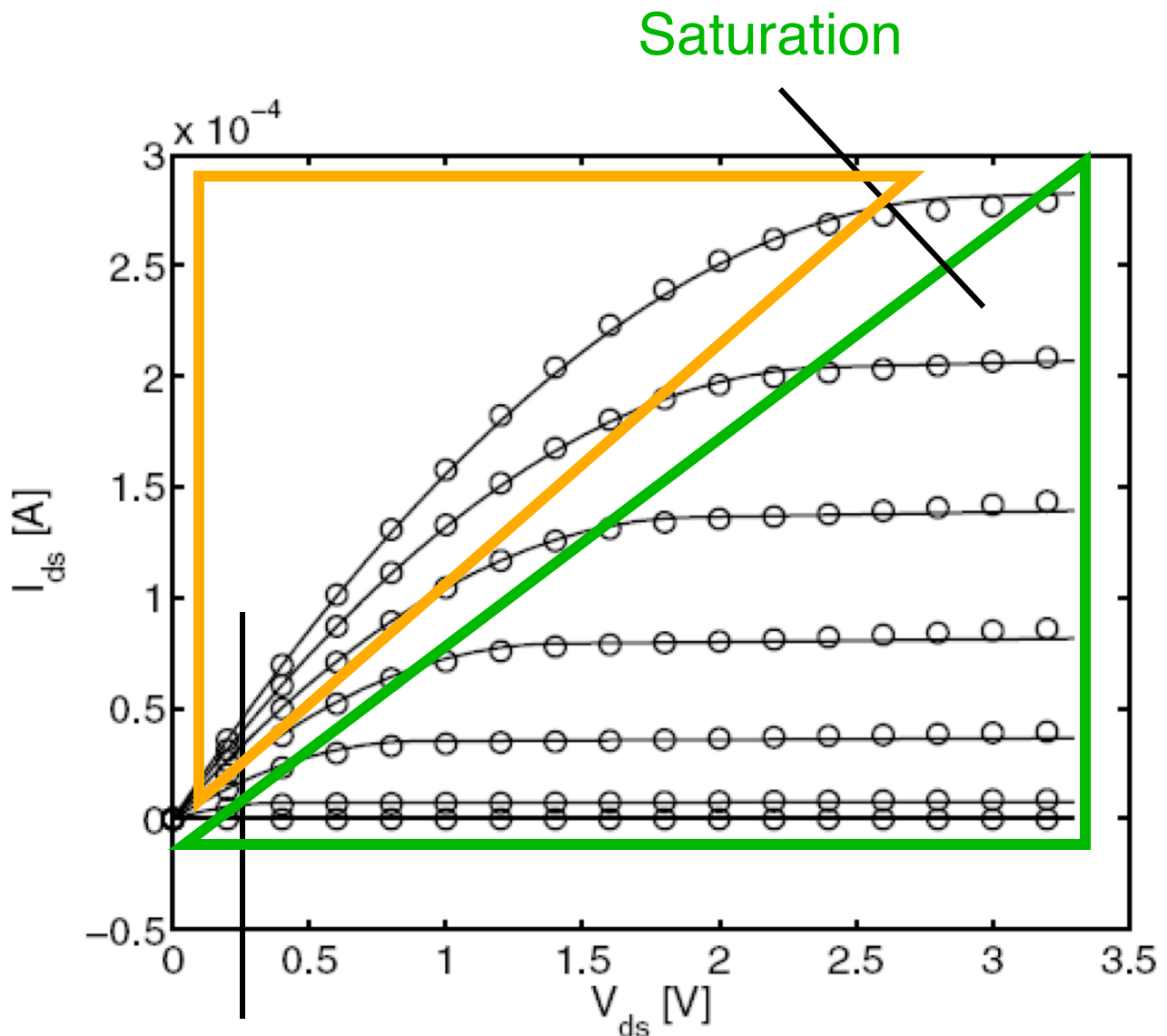
Device operation characterized by the form of the current as a function of the bias voltage between the gate and the source terminals (V_{GS})



Weak Inversion (also known as Subthreshold)

Conduction (vs) Saturation

Device operation characterized by the form of the current as a function of the bias voltage between the DRAIN and the source terminals (V_{ds})



Conduction (also known as Ohmic)

MOS Model (above threshold): simple and non-symmetric!

$$\text{If } V_{GS} < 0$$

$$I_{DS} = 0$$

$$\text{If } V_{DS} > V_{GS} - V_{TO}$$

$$I_{DS} = \left(\frac{W}{L}\right) \left(\frac{UO}{2}\right) \frac{\epsilon_0 \epsilon_r}{TOX} (V_{GS} - V_T)^2$$

$$\text{If } V_{DS} < V_{GS} - V_{TO}$$

$$I_{DS} = \left(\frac{W}{L}\right) UO \frac{\epsilon_0 \epsilon_r}{TOX} \left((V_{GS} - V_T) V_{DS} - \frac{V_{DS}^2}{2} \right)$$

$$V_T = V_{TO} + GAMMA \left(\sqrt{PHI - V_{BS}} - \sqrt{PHI} \right)$$

$\epsilon_0 = 8.85 \cdot 10^{-12}$ F/m is the absolute permittivity

ϵ_r = relative permittivity, equal to 3.9 in the case of SiO2 (no unit)

Mos Model 1 parameters			
Parameter	Definition	Typical Value 0.12 μ m	
		NMOS	PMOS
VTO	Theshold voltage	0.4V	-0.4V
U0	Carrier mobility	0.06m ² /V-s	0.02m ² /V-s
TOX	Gate oxide thickness	2nm	2nm
PHI	Surface potential at strong inversion	0.3V	0.3V
GAMMA	Bulk threshold parameter	0.4 V ^{0.5}	0.4 V ^{0.5}
W	MOS channel width	1 μ m	1 μ m
L	MOS channel length	0.12 μ m	0.12 μ m

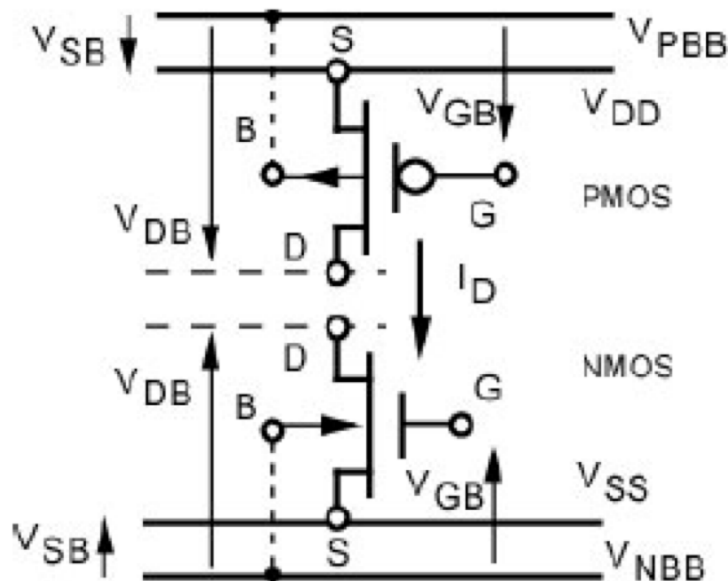
MOS Model (sub-threshold)

NMOS

$$I_D \equiv I_{DS} = S I_{n0} \exp\left(\frac{\kappa_n V_{GB}}{V_t}\right) \left[\exp\left(\frac{-V_{SB}}{V_t}\right) - \exp\left(\frac{-V_{DB}}{V_t}\right) \right]$$

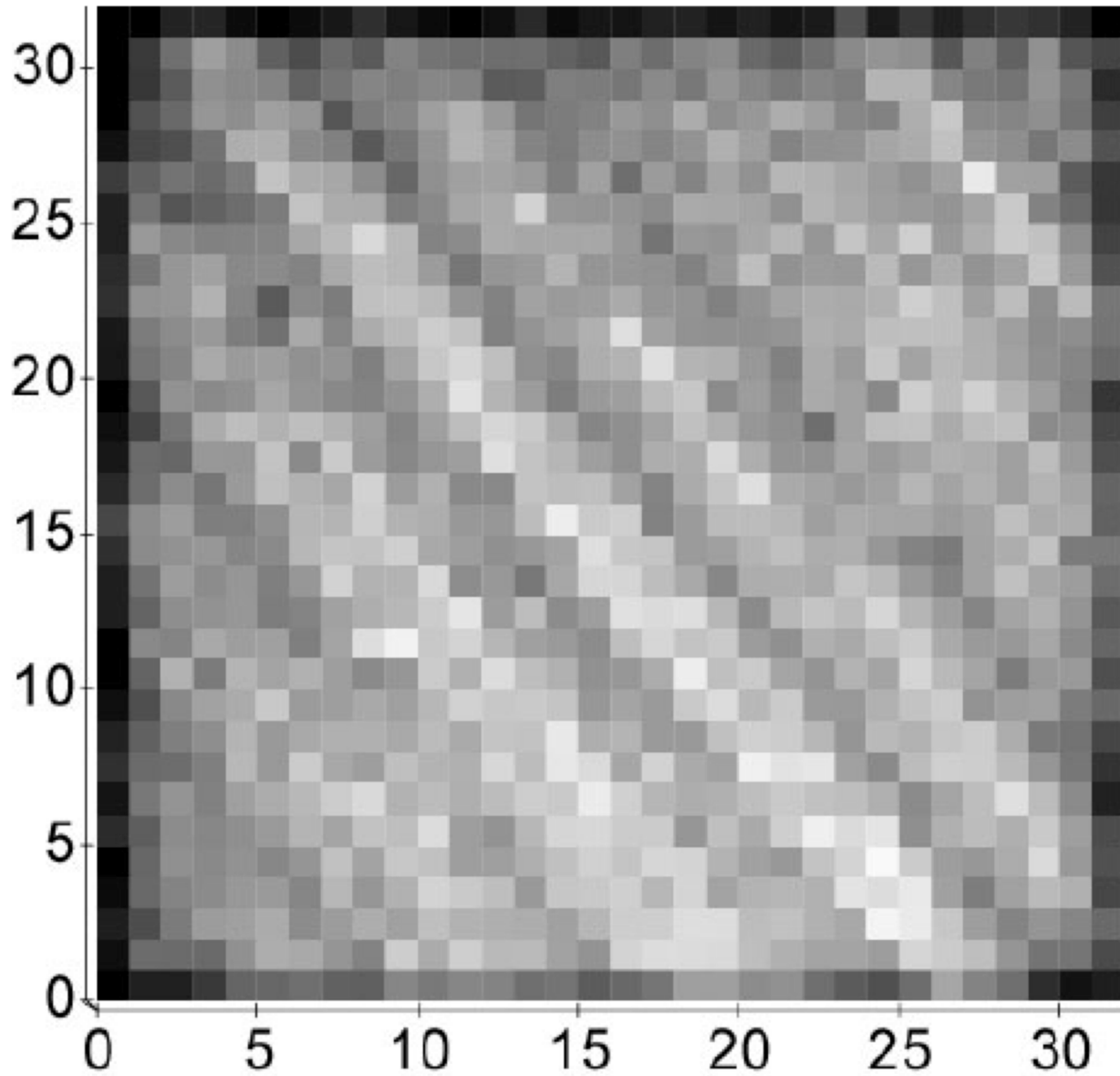
PMOS

$$I_D \equiv I_{SD} = S I_{p0} \exp\left(\frac{-\kappa_p V_{GB}}{V_t}\right) \left[\exp\left(\frac{V_{SB}}{V_t}\right) - \exp\left(\frac{V_{DB}}{V_t}\right) \right]$$

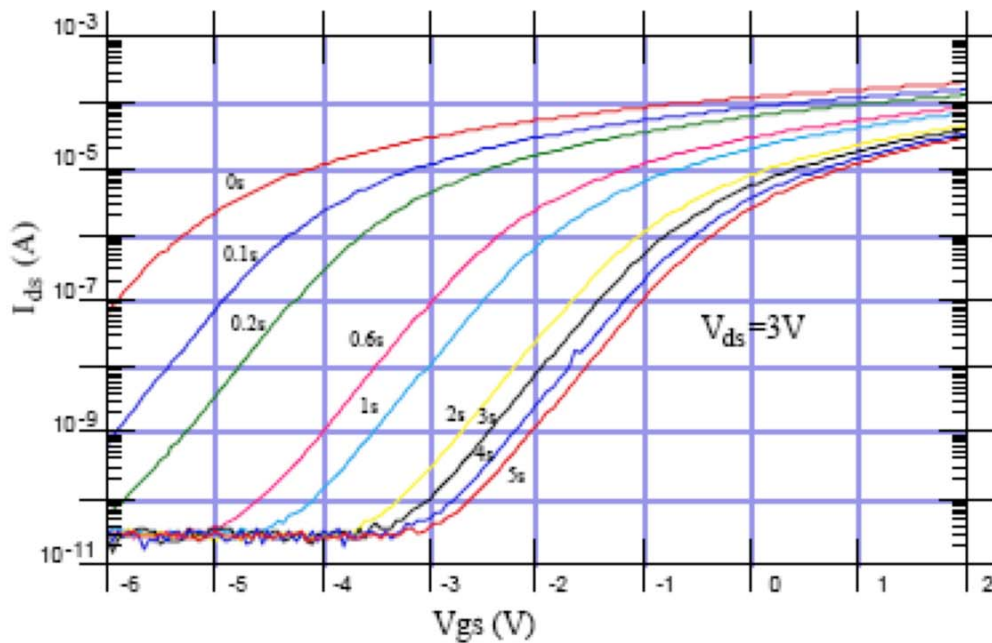
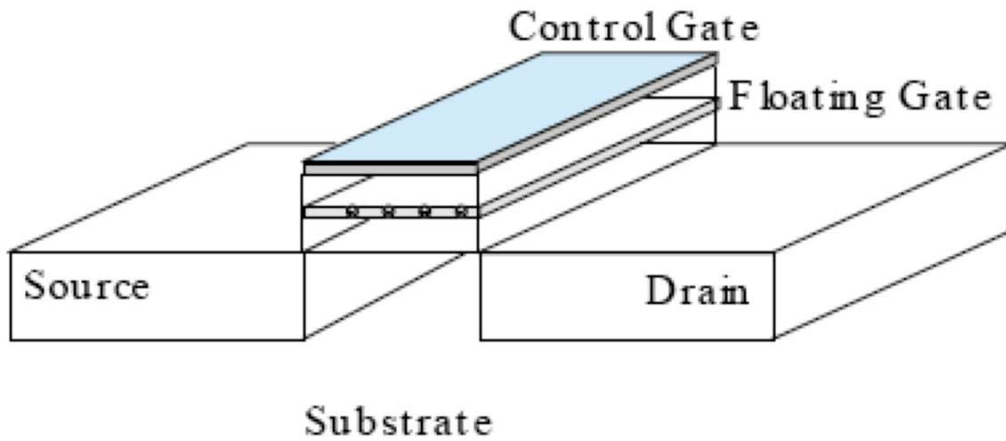


$$V_t \equiv \frac{kT}{q} \quad \kappa \equiv \frac{1}{\eta} \equiv \frac{C_{ox}}{C_{ox} + C_{dep}} \quad S = \frac{W}{L}$$

MOS MISMATCH

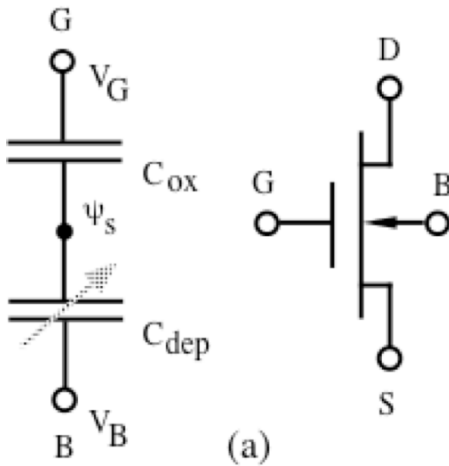


FLOATING GATE MOS (FGMOS)

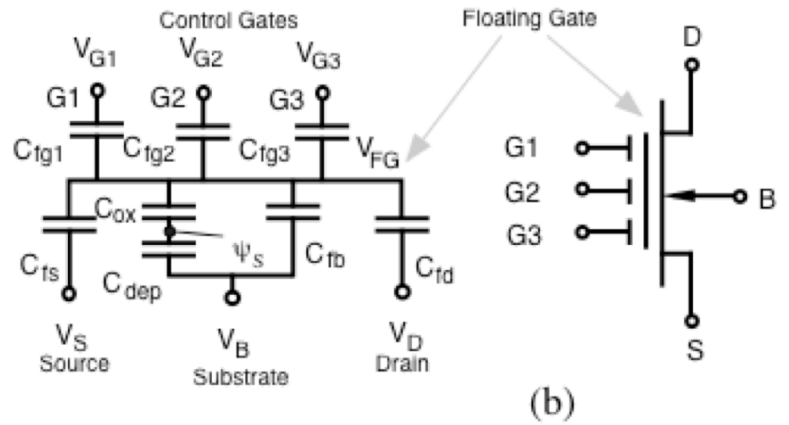


MOS CAPACITANCE MODEL

MOS



FGMOS



$$V_{FG_i} = \frac{Q_{FG_i}}{C_{T_i}} + \sum_{j=1}^N \Lambda_{ij} V_{G_j}$$

$$\Lambda_{ij} = \frac{C_{fg}}{C_{T_i}}$$